ASOCIATION CONNECTING ELECTRONICS INDUSTRIES® international and P	IPC, Bannockl	burn, Illinois. A	Il rights reserved nations.	under both	This docum level parts, t	ent is a declara he declaration	tion of the s encompasse	ubstances es all lowe	within the manuf r level materials f	acturer liste or which th	ed item. Note e manufactur	: if the item is an a rer has engineering	ssembly with low responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form http://www.ipc.org/IPC-175x Distri								aterials and	ials and Mfg Information				
Supplier Information														
Company name* Com			Company unique ID			Unique ID Authority				Resp	Response Date*			
onsemi										2024	2024-05-02			
Contact Name Title - Cont			- Contact			Phone - Contact*				Emai	Email - Contact*			
Product-Env-Stewards Product En			act Enviro Compliance			NA				Prod	Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Repr			- Representative			Phone - Representative*			Emai	Email - Representative*				
Product-Env-Stewards Product Er			duct Enviro Compliance			NA				Prod	Product-Env-Stewards@onsemi.com			
Requester Item Number	Requester Item Number Mfr Item		Number Mfr Item Name			Effective Dat	e Version	.]	Manufacturing Site		Weight*	UOM	Unit Type	
	QSB34C	QSB34GR PI		PHOTODIODE PLCC2 DAY		2024-05-02		1	EVERLGFG		46.58	mg	Each	
Aanufacturing Proccess Inform	ation						-				·			
Terminal Plating / Grid Array M	Terminal Plating / Grid Array Material Terminal Base A		Alloy	J-STD-020 MSL Rating		Peak Process Body Temperature		re Max Time at I	Time at Peak Temperature Number of Reflow Cycles		cles			
Matte Tin (Sn) - annealed CU Alloy		CU Alloy	3			260 C		30	see	seconds 3				
omments														
TTENTION: MSL 3 Rated item requin	es Bake and L	Dry Pack (after	electrical test)											
or more information regarding materia	l composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chror	HS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl thalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.05	mg	Supplier	Silicon (Si)	7440-21-3		0.05	mg
Die Attach	0.05	mg	Supplier	Silver (Ag)	7440-22-4		0.045	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.005	mg
Lead Frame	19.698	mg	Supplier	Silver (Ag)	7440-22-4		0.006	mg
			Supplier	Zinc (Zn)	7440-66-6		0.026	mg
			Supplier	Iron (Fe)	7439-89-6		0.473	mg
			Supplier	Copper (Cu)	7440-50-8		19.193	mg
Mold Compound-Black	25.772	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		12.886	mg
			Supplier	2,4,6-Tris[Bis(Methoxymethyl)Amino]- 1,3,5-Triazine	3089-11-0		12.886	mg
Plating	1.0	mg	Supplier	Tin (Sn)	7440-31-5		1	mg
Wire Bond - Au	0.01	mg	Supplier	Gold (Au)	7440-57-5		0.01	mg